

L. Nelson
#5/Pre Amdt. B
4-15-02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of Applicants:

Beaman et al.

Serial No.: 09/921,867

Filed: August 3, 2001

For: HIGH DENSITY INTEGRATED CIRCUIT APPARATUS,
TEST PROBE AND METHODS OF USE THEREOF

Date: April 9, 2002

Group Art Unit: 3729

Examiner:

Docket No.: YOR919930028US6

Assistant Commissioner for Patents
Washington, D. C. 20231

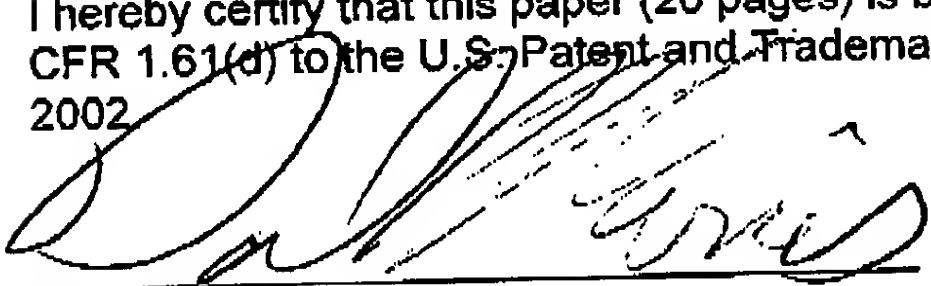
FAX RECEIVED

APR - 9 2002

GROUP 3100

CERTIFICATE OF FACSIMILE TRANSMISSION

I hereby certify that this paper (20 pages) is being facsimile transmitted under Rule 37
CFR 1.61(d) to the U.S. Patent and Trademark Office to (703) 872-9302 on April 9,
2002.


Dr. Daniel P. Morris, Esq.
Reg. No. 32,053SECOND PRELIMINARY AMENDMENT

IN THE CLAIMS

Add the following claims:

3
67. (Added) An assembly including an electronic component, the electronic
component comprising:

a plurality of contact locations adjacent a surface of the electronic component,

01 FC:103

1278.00 CH

02 FC:102

756.00 CH

Serial No. 09/921,867

1

Docket No. YOR919930028US6

Received from < > at 4/9/02 3:42:00 PM [Eastern Daylight Time]